

Claims 1-64: Canceled.

65. (New) A layered material, comprising:
an interface material for electronic devices comprising at least one resin material and at least about 50 weight percent of at least one solder material, and
at least one additional layer.
66. (New) The layered material of claim 65, wherein the interface material further comprises at least one wetting enhancer.
67. (New) The layered material of claim 65, wherein the at least one resin material comprises a silicone resin.
68. (New) The layered material of claim 67, wherein the silicone resin comprises a vinyl terminated siloxane, a reinforcing additive, a crosslinker and a catalyst.
69. (New) The layered material of claim 68, wherein the vinyl terminated siloxane is vinyl silicone.
70. (New) The layered material of claim 68, wherein the reinforcing additive is vinyl Q resin.
71. (New) The layered material of claim 68, wherein the crosslinker comprises a hydride functional siloxane.
72. (New) The layered material of claim 68, wherein the catalyst comprises a platinum complex.
73. (New) The layered material of claim 72, wherein the platinum complex is a platinum-vinylsiloxane compound.
74. (New) The layered material of claim 66, wherein the wetting enhancer comprises an organo-titanite compound.
75. (New) The layered material of claim 65, wherein the at least one solder material comprises an indium-based alloy or compound.

76. (New) The layered material of claim 75, wherein the indium-based alloy or compound comprises InSn, InAg or In.
77. (New) The layered material of claim 65, wherein the at least one solder material comprises a tin-based alloy or compound.
78. (New) The layered material of claim 77, wherein the tin-based alloy or compound / comprises SnAgCu or SnBi.
79. (New) The layered material of claim 65, wherein the interface material comprises one of an aluminum or an aluminum-based alloy or compound.
80. (New) The layered material of claim 65, wherein the interface material comprises a filler material.
81. (New) The layered material of claim 80, wherein the interface material comprises carbon.
82. (New) The layered material of claim 81, wherein the filler material comprises carbon microfibers, carbon nanotubes or a combination thereof.
83. (New) The layered material of claim 65, wherein the interface material has a viscosity that exceeds 450 poises.
84. (New) The layered material of claim 65, wherein the interface material has a thermal impedance of less than $0.3 \text{ cm}^2\text{C/w}$.
85. (New) The layered material of claim 65, wherein the interface material further comprising gallium.
86. (New) The layered material of claim 65, wherein the at least one solder material is present in an amount of at least about 60 weight percent.

87. (New) The layered material of claim 86, wherein the at least one solder material is present in an amount of at least about 70 weight percent.
88. (New) The layered material of claim 87, wherein the at least one solder material is present in an amount of at least about 80 weight percent.